

L Number	Hits	Search Text	DB	Time stamp
1	4	underfill\$4 and semiconductor and (carrier adj substrate)and (liquid adj resin)	USPAT	2004/06/09 13:48
2	7	underfill\$4 and semiconductor and (carrier adj substrate)and (liquid adj resin)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/09 13:48